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02/22/2002

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PA

AUG 26 2003

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	CAU	EXAMINER
10081425	02/22/2002	08	127	282	

APPLICANTS: Pendse Rajendra;

SBG

CONTINUING DATA VERIFIED:

THIS APPLN CLAIMS BENEFIT OF 60/272,280 02/27/2001

SBG

FOREIGN APPLICATIONS VERIFIED:

NONE

SBG

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed

☐ yes ☒ no

35 USC 119 conditions met

☐ yes ☒ no

Verified and Acknowledged Examiners's initials

SBG

ATTORNEY DOCKET NO

CPAC 1011-2 US

TITLE : Apparatus and process for precise encapsulation of flip chip interconnects

NOTICE OF ALLOWANCE MAILED

ISSUE FEE

Amount Due

\$ 1600

Date Paid

5/14/03



TERMINAL

DISCLAIMER

Formal Drawings:

DRAWINGS

Sheets Drwg.

Figs. Drwg.

Print Fig.

CLAIMS ALLOWED

Total Claims

Print Claim for O.G.

NOTICE OF ALLOWANCE MAILED

ISSUE FEE

Amount Due

Date Paid

ISSUE BATCH NUMBER

FILED WITH:

☐ DISK (CRF)

☐ CD-ROM
(Attached in pocket on right inside flap)